

METHOD FOR PACKAGING SMALL SIZE MEMORY CARDS

ABSTRACT

The present invention provides methods for packaging small size memory cards wherein the methods comprise molding over a populated printed circuit board, thereby an encapsulated memory card is obtained with desirable external dimensions and features. In one aspect of the invention, methods are provided for preventing mold bleed underneath of the contact pads of memory cards. In one embodiment, the mold bleeding is prevented by using slidable holding pins that exert pressure directly upon the contact pins during the molding process. In another embodiment, the mold bleeding is prevented by covering the contact pads with temporary substrate coverage during the molding process. In yet another embodiment, the mold bleeding is prevented by using pressing edges that exert pressure directly upon the area of contact pads during the molding process. In still another embodiment, the mold bleeding is prevented by using vacuum pressure to secure the populated PCB onto the bottom of a molding apparatus. In yet still another embodiment, the mold bleeding is prevented by mounting dummy components onto the area opposite to the contact pads in a populated PCB, thereby the dummy components exert direct pressure to the contact pads during the molding process.

FIG 2